



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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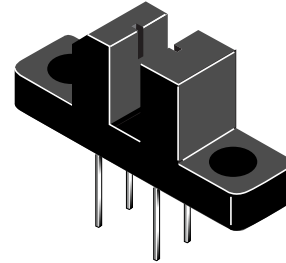
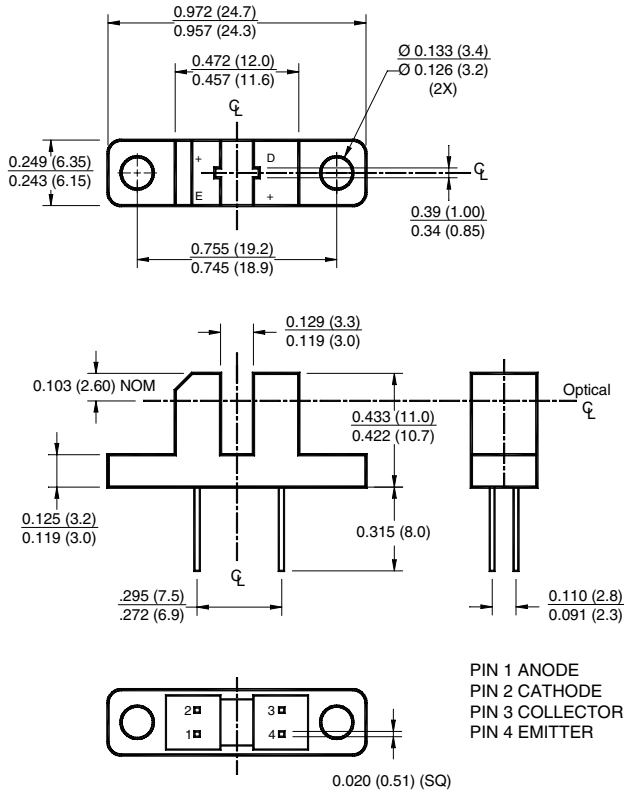
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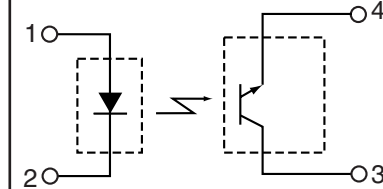
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PACKAGE DIMENSIONS



SCHEMATIC



NOTES:

1. Dimensions for all drawings are in inches (mm).
2. Tolerance of $\pm .010$ (.25) on all non-nominal dimensions unless otherwise specified.

DESCRIPTION

The CNY28 is a gallium arsenide infrared emitting diode coupled with a silicon phototransistor in a plastic housing. The gap in the housing provides a means of interrupting the signal with tape, cards, shaft encoders or other opaque material, switching the output from an "ON" to an "OFF" state.

FEATURES

- Opaque housing
- Low cost
- 0.035" apertures
- European "Pro Electron" registered

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Rating	Units
Operating Temperature	T_{OPR}	-55 to +85	$^\circ\text{C}$
Storage Temperature	T_{STG}	- 55 to +85	$^\circ\text{C}$
Soldering Temperature (Iron) ^(2,3,4)	T_{SOL-I}	240 for 5 sec	$^\circ\text{C}$
Soldering Temperature (Flow) ^(2,3)	T_{SOL-F}	260 for 10 sec	$^\circ\text{C}$
INPUT (EMITTER)			
Continuous Forward Current	I_F	50	mA
Reverse Voltage	V_R	6	V
Power Dissipation ⁽¹⁾	P_D	100	mW
OUTPUT (SENSOR)			
Collector-Emitter Voltage	V_{CEO}	30	V
Emitter- Collector Voltage	V_{ECO}	4.5	V
Collector Current	I_C	20	mA
Power Dissipation ⁽¹⁾	P_D	150	mW

NOTES:

- Derate power dissipation linearly 1.67 mW/ $^\circ\text{C}$ above 25 $^\circ\text{C}$.
- RMA flux is recommended.
- Methanol or isopropyl alcohols are recommended as cleaning agents.
- Soldering iron 1/16" (1.6mm) from housing.

ELECTRICAL / OPTICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$)

PARAMETER	TEST CONDITIONS	SYMBOL	MIN	TYP	MAX	UNITS
INPUT (EMITTER)						
Forward Voltage	$I_F = 10\text{ mA}$	V_F	—	—	1.7	V
Reverse Leakage Current	$V_R = 2\text{ V}$	I_R	—	—	10	μA
OUTPUT (SENSOR)						
Emitter-Collector Breakdown	$I_E = 100\ \mu\text{A}$, $E_e = 0$	BV_{ECO}	5.0	—	—	V
Collector-Emitter Breakdown	$I_C = 10\text{ mA}$, $E_e = 0$	BV_{CEO}	30	—	—	V
Collector-Emitter Leakage	$V_{CE} = 10\text{ V}$, $E_e = 0$	I_{CEO}	—	—	100	nA
COUPLED						
Collector Current	$I_F = 20\text{ mA}$, $V_{CE} = 10\text{ V}$	$I_{C(ON)}$	0.20	—	—	mA
Collector Emitter Saturation Voltage	$I_F = 20\text{ mA}$, $I_C = 25\ \mu\text{A}$	$V_{CE(SAT)}$	—	—	0.40	V
Turn-On Time	$I_F = 30\text{ mA}$, $V_{CC} = 5\text{ V}$, $R_L = 2.5\text{ k}\Omega$	t_{on}	—	5	—	μs
Turn-Off Time	$I_F = 30\text{ mA}$, $V_{CC} = 5\text{ V}$, $R_L = 2.5\text{ k}\Omega$	t_{off}	—	5	—	μs

TYPICAL PERFORMANCE CURVES

Fig. 1 Output Current vs. Input Current

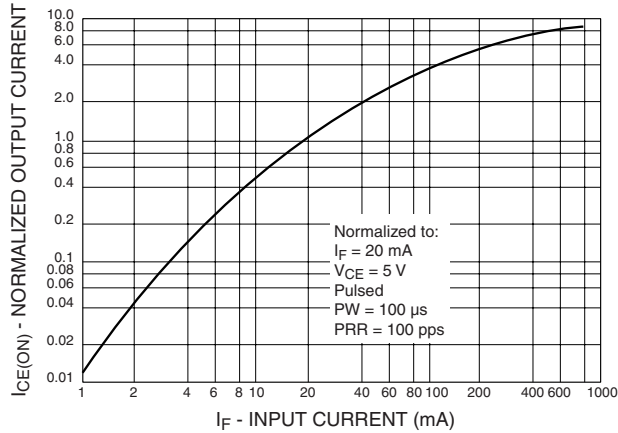


Fig. 2 Output Current vs. Temperature

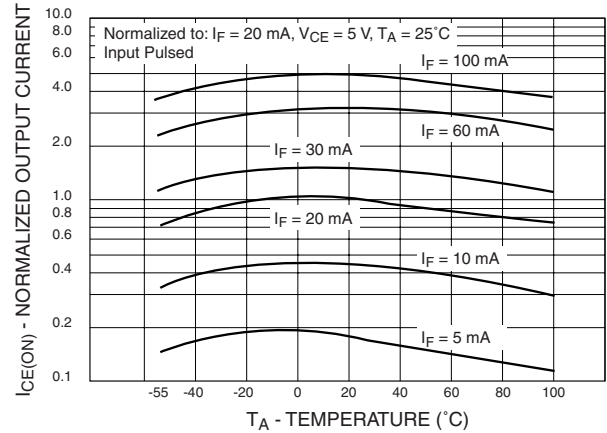


Fig. 3 Saturation Voltage vs. Ambient Temperature

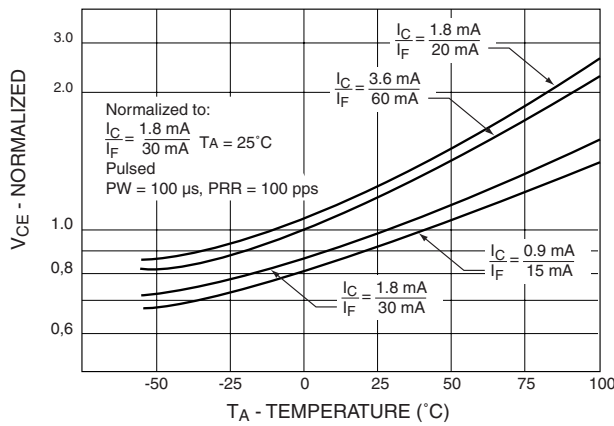


Fig. 4 Normalized Dark Current vs. Ambient Temperature (Detector)

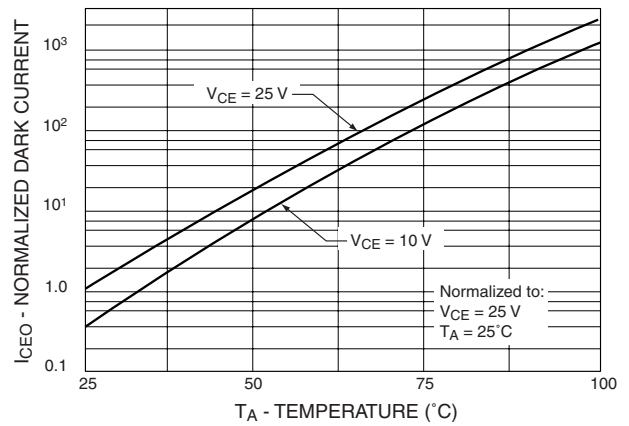
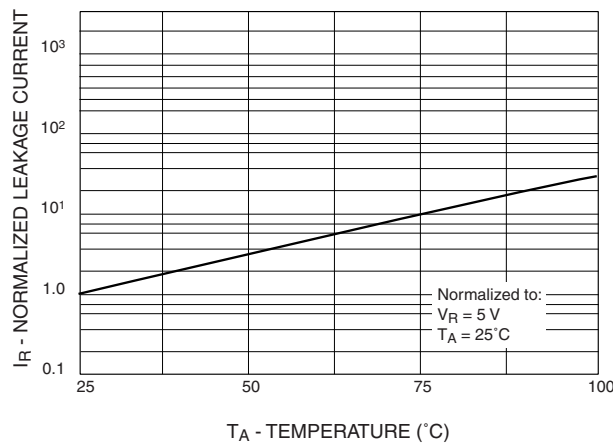


Fig. 5 Normalized Leakage Current vs. Ambient Temperature (Emitter)



TYPICAL PERFORMANCE CURVES

Fig. 6 Switching Time vs. Load Resistance

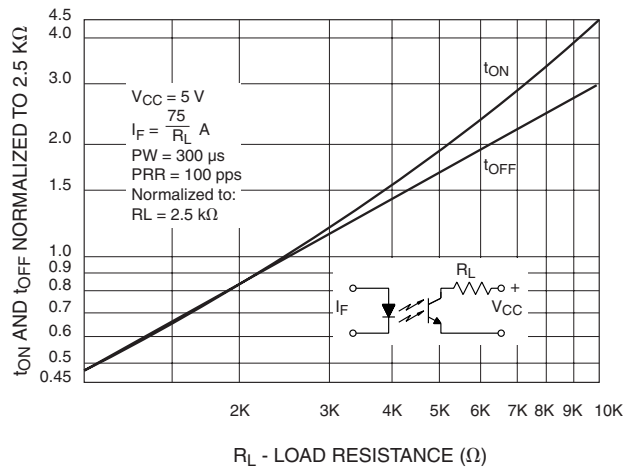
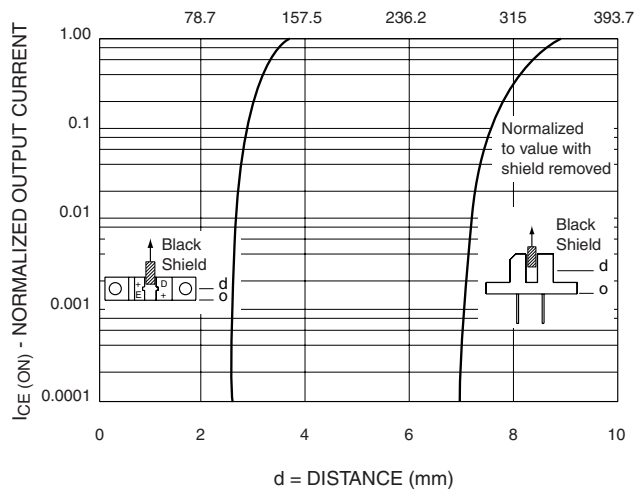


Fig. 7 Output Current vs. Distance



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